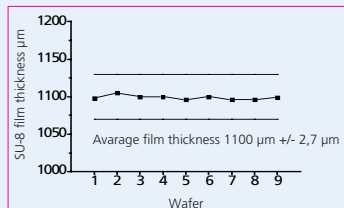


The Experts for Photoresists

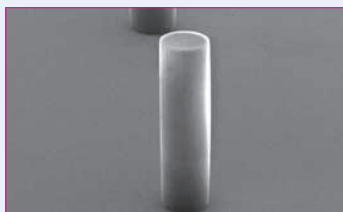
Innovation



Highly reproducible film thickness in a series of SU-8 coated wafers



Preparation of a 1000 µm thick resist layer



UV imaging of a 300 µm thick SU-8 layer



UV imaging of a 30 µm thick micro coil



Electroformed Nickel coil - 30 µm



Mikrowave-plasma processor TEPLA 300 SEMI AUTO

Quality

Analytical services

- UV/Vis and NIR spectroscopy of solutions and films
- Scanning electron microscopy – characterisation with a magnification of up to 30.000

Photoresist modification

- ORMOCER®s with changed polymerisation initiator
- Customised ORMOCER® solutions (variation of film thickness)
- Customised resist solutions based on epoxy resins (SU-8), e.g. solvent variation
- Dyed photoresist solutions

Lithographic services

- Coating of different substrates (e.g. silicon, glass, ceramics, foils) with photoresists/polymers
 - Spin coating (5 inch)
 - Doctor blading (15 cm x 30 cm)
- Preparation of ultra-thick resist films
 - Positive tone photoresists from 1 µm to 60 µm
 - Epoxies (SU-8) from 0.5 µm to 1500 µm
- Innovative bake processes by using of an Infrared baker (4 inch – 6 inch wafer)
- UV lithographic patterning (4 inch wafer)
 - SU-8 films up to 300 µm
 - Positive tone photoresist films up to 50 µm
 - Negative tone photoresist films up to 10 µm

O₂-plasma processing

- Service with microwave-plasma system (TEPLA)
- Removal of photoresists and polymers

Lithographic equipment

- Microwave-plasma processor TEPLA 300 SEMI AUTO
- Coating systems with and without Gyrset up to a substrate size of 5 inch
- Bake systems:
 - Programmable precision hotplates
 - Infrared baker
 - Convection ovens
- Exposure tool maskaligner SUSS MA 56 M
- Film thickness measurement - DEKTAK (profilometer) for films up to 300 µm
- FTP 500 (ellipsometer) for films up to 3 µm
- Nickel electroforming (Ni-sulfamate) of 4-inch wafers – film thickness up to 80 µm